



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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CHO-BOND® 1019

TWO COMPONENT ELECTRICALLY CONDUCTIVE SILVER-PLATED ALUMINUM POLYTHIOETHER SEALANT



Customer Value Proposition:

CHO-BOND 1019 is a silver plated aluminum filled, two-component conductive polythioether designed for use as a fillet, gap filler and seam sealant on military shelters and electrical enclosures for EMI shielding. The silver aluminum filler of CHO-BOND 1019 provides excellent galvanic corrosion resistance when applied to aluminum substrates. In addition, CHO-BOND 1019's custom formulated polythioether polymer system is paintable – eliminating the need and cost of an additional primer application step before painting. CHO-BOND 1019 cures to the touch in 24hrs and provides a robust conductive and environmental seal over a wide range of application temperatures. CHO-BOND 1019 has been qualified on hexavalent chromium IAW MIL-DTL-5541 Class 1A and trivalent chromium IAW MIL-DTL-5541 Type II Class 3 in harsh conditions including heat, humidity, and salt fog where it maintains stable EMI shielding performance. Overcoat adhesion qualified with MIL-PRF-23377 Type II Class N and MIL-DTL-53022 Type II epoxy primers. Minimum recommended bond line for CHO-BOND 1019 is 0.010 inches (0.25mm).

Contact Information:

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Features and Benefits:

- Two component
- Silver/Aluminum filler
- Paintable
- Good EMI shielding
- Low VOCs
- Polythioether
- Light weight
- Dry medium paste
- Packaged in a pre-measured kit. No weighing required, mix and dispense in same package, minimizes process scrap.
- Excellent galvanic corrosion resistance against aluminum substrates.
- Eliminates additional primer application process and cure time.
- >80 dB EMI shielding from 300 Mhz to 18 GHz.
- Minimal shrinkage, no permits or ventilation required
- 120 minute working life, rapid skin formation, 24 hr handling time, requires no pressure during curing, wide range of application temperatures.
- More coverage per gram of material, minimal weight added to assembly or vehicle
- Can be used on overhead or vertical surfaces.



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CHO-BOND 1019 - Preliminary Product Information

Table 1 Typical Properties

| CHO-BOND 1019 | | |
|---|------------------------------------|-----------------------|
| Typical Properties | Typical Values | Test Method |
| Polymer | Polythioether | N/A |
| Filler | Silver Aluminum | N/A |
| Mix Ratio, A : B (by weight) | 2-part | N/A |
| Color | A: White, B: Black | N/A (Q) |
| Consistency | Medium Paste | N/A (Q) |
| Maximum DC Volume Resistivity | 0.01 ohm-cm | CHO-95-40-5555* (Q/C) |
| Minimum Lap Shear Strength** | 65 psi (448 kPa) | CHO-95-40-5300* (Q/C) |
| Specific Gravity | 2.15 | ASTM D792 (Q/C) |
| Hardness Shore A | 72 (±8) | ASTM-D2240 (Q/C) |
| Continuous Use Temperature | - 62°C to 160°C (-80 °F to 320 °F) | N/A (Q) |
| Elevated Temperature Cure Cycle | None | N/A |
| Room Temperature Cure | 1 week** | N/A (Q) |
| Working Life | 2 hours | N/A (Q) |
| Tack Free Time | 8 hours | N/A (Q) |
| 50% Cure Time | 16 hours | N/A (Q) |
| Time to Paint Over | 3 days*** | N/A (Q) |
| Shelf Life, frozen -40°C (-40°F) unopened | 6 months | N/A (Q) |
| Minimum thickness recommended | 0.010 in (0.25 mm) | N/A |
| Maximum thickness recommended | 0.250 in (6.35 mm) | N/A |
| Volatile Organic Content (VOC) | 124 g/l | Calculated |

Notes: N/A – Not Applicable, (Q/C) – Qualification and Conformance Test, (Q) – Qualification Test

* This test Method is available from Parker Chomerics.

** Cure is sufficient for handling in 24 hours. Full specification properties are developed after 1 week (168 hours) at room temperature.

*** Chomerics' recommend minimum time to wait before applying paint over CHO-BOND 1019. Material will continue to cure after painting.

Table 2 Ordering Information

| Product | Weight (grams) | Packaging | Part Number | Primer Included |
|---------------|----------------|---|-----------------|-----------------|
| CHO-BOND 1019 | 280 | 6 fluid ounce SEMCO cartridge with dasher rod | 50-01-1019-0000 | Not required |

Please refer to Parker Chomerics Surface Preparation and CHO-BOND Application documents for information regarding the proper surface preparation, primer application (if required), and use of these compounds.

www.chomerics.com

www.parker.com/chomerics

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